

$\frac{d}{dt} \left(\frac{\partial L}{\partial \dot{x}} \right) = \frac{\partial L}{\partial x}$

A⁹

A⁴

5

-- thermocompression --.

Figs. 31, 32 and 33 are diagrammatic, perspective views depicting further embodiments according to the invention.~

IN THE ABSTRACT:

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ABSTRACT OF

A semiconductor chip assembly, comprises a first semiconductor chip having a front surface, a rear surface and contacts on the front surface and a second semiconductor chip having a front surface, a rear surface and contacts on the